Quik-Pak™
Microelectronic Packaging & Assembly Solutions

Press Release

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FOR IMMEDIATE RELEASE
9 A.M. EDT, November 12, 2010

Quik-Pak Expands Wire Bonding Capabilties

San Diego, CA, November 12, 2010, - Quik-Pak, a division of Delphon Industries and leader in Microelectronic Packaging and Assembly, has expanded its already robust wire bonding services with new state-of-the-art K&S equipment. This new equipment is capable of handling wire diameters from 0.7 mil (18µm) to 3.0 mils (76µm) and bond pad pitch down to 35 microns.

Quik-Pak performs Gold and Copper ball wire bonding as well as Aluminum wedge bonding with 0.8 mil - 2.0mil wire, and can even combine Gold, Copper and Ribbon bonding in the same device. “Quik-Pak is constantly striving to enhance its operations to include system solutions to the new technology challenges inherent in assembling and packaging next-

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generation semiconductors," says Steve Swendrowski, Quik-Pak General Manager.

About Quik-Pak:

The company specializes in microelectronic packaging and advanced assembly services. A limitless array of open-cavity and open molded packages are available with no minimum quantity. Packaging can be provided as part of a turnkey assembly solution along with backgrinding, wafer dicing, die/wire bonding, laser micromachining, remolding and marking/branding. Custom assembly services are also offered for flip chip, ceramic packages, chip-on-board, stacked die, MEMS, etc. Quik-Pak's unique offerings deliver faster time to market and reduced costs for new devices, while providing excellent flexibility, quality and customer service.

For further information:

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